



A Product Line of **Diodes Incorporated** 



# **BSS138**

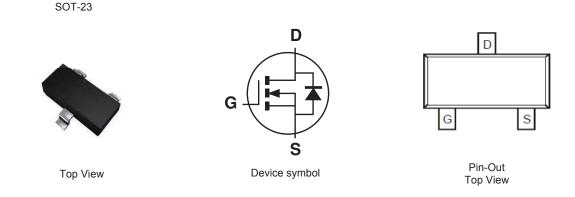
#### **50V N-CHANNEL ENHANCEMENT MODE VERTICAL DMOS FET IN SOT23**

#### **Features and Benefits**

- BV<sub>DSS</sub> > 50V •
- $R_{DS(on)} \le 3.5\Omega @ V_{GS} = 5V$ .
- Maximum continuous drain current I<sub>D</sub> = 200mA .
- "Lead Free", RoHS Compliant (Note 1)
- Halogen and Antimony Free. "Green" Device (Note 2)
- Qualified to AEC-Q101 Standards for High Reliability

# **Mechanical Data**

- Case: SOT-23 •
- Case Material: Molded Plastic, "Green" Molding Compound. • UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matt Tin Finish; Solderable per MIL-STD-202, • Method 208
- Weight: 0.008 grams (approximate) .



Ordering Information (Note 3)					
Part Number	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel	
BSS138TA	SS	7	8	3000	

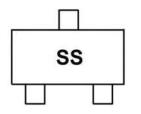
1. No purposefully added lead

2. Diodes Inc's "Green" policy can be found on our website at http://www.diodes.com.

3. For packaging details, go to our website at http://www.diodes.com.

## **Marking Information**

Notes:



SS = Product Type Marking Code





**BSS138** 

## Maximum Ratings @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Drain-Source Voltage	V <sub>DSS</sub>	50	V
Gate-Source Voltage	V <sub>GSS</sub>	±20	V
Continuous Drain Current	ID	200	mA
Pulsed Drain Current (Note 5)	I <sub>DM</sub>	800	mA

## Thermal Characteristics @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic		Symbol	Value	Unit
Power Dissipation	(Note 4)	PD	350	mW
Thermal Resistance, Junction to Ambient	(Note 4)	R <sub>0JA</sub>	357	°C/W
Thermal Resistance, Junction to Leads	(Note 6)	R <sub>θJL</sub>	195	°C/W
Operating and Storage Temperature Range		T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

Notes: 4. For a device mounted on 25mm X 25mm X 1.6mm FR-4 PCV with high coverage of single sided 1oz copper, in still air condition.

5. Device mounted on minimum recommended pad layout test board, 10µs pulse duty cycle = 1%.

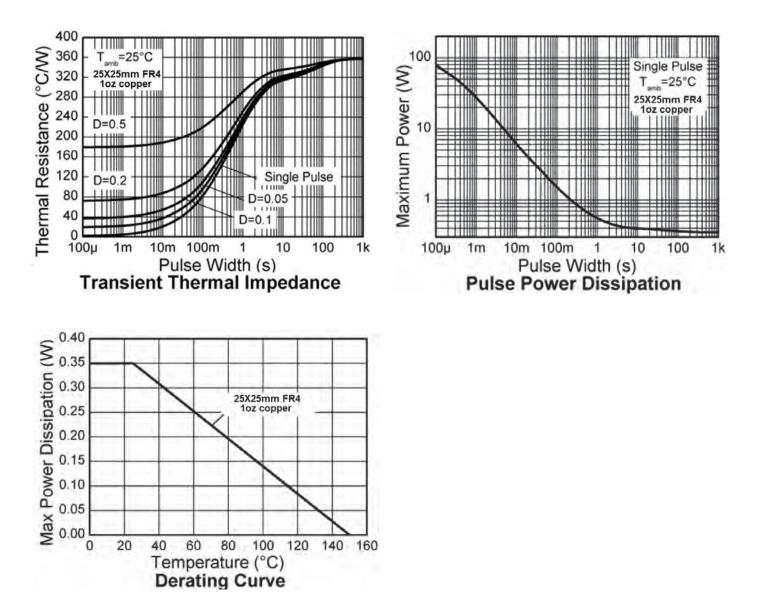
6. Thermal resistance from junction to solder-point (at the end of the collector lead).







## **Thermal Characteristics**







**BSS138** 

# **Electrical Characteristics** @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	50	-	-	V	V <sub>GS</sub> = 0V, I <sub>D</sub> = 0.25mA	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	-	-	0.5 5 100	μA μA nA		
Gate-Source Leakage	Igss	-	-	±100	nA	$V_{GS}$ = ±20V, $V_{DS}$ = 0V	
ON CHARACTERISTICS							
Gate Threshold Voltage	V <sub>GS(th)</sub>	0.5	-	1.5	V	$V_{DS} = V_{GS}$ , $I_D = 1mA$	
Static Drain-Source On-Resistance (Note 7)	R <sub>DS (on)</sub>	-	-	3.5	Ω	V <sub>GS</sub> = 5V, I <sub>D</sub> = 200mA	
Forward Transconductance (Note 7 & 8)	<b>g</b> fs	120	-	-	mS	V <sub>DS</sub> = 25V, I <sub>D</sub> = 200mA	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	C <sub>iss</sub>	-	-	50	pF	V <sub>DS</sub> = 25V, V <sub>GS</sub> = 0V, f = 1.0MHz	
Output Capacitance	Coss	-	-	25	pF		
Reverse Transfer Capacitance	C <sub>rss</sub>	-	-	8	pF		
Turn-On Delay Time (Note 9)	t <sub>D(on)</sub>	-	10	-	ns	V <sub>DD</sub> = 30V, I <sub>D</sub> = 280mA	
Turn-On Rise Time (Note 9)	tr	-	10	-	ns		
Turn-Off Delay Time (Note 9)	t <sub>D(off)</sub>	-	15	-	ns		
Turn-Off Fall Time (Note 9)	t <sub>f</sub>	-	25	-	ns		

Notes:

7. Measured under pulsed conditions. Width =  $300\mu$ s. Duty cycle  $\leq 2\%$ .

8. Sample test.

9. Switching times measured with  $50\Omega$  source impedance and <5ns rise time on a pulse generator.



0.1

**Drain Current** 

Vos =25V

4

0

40

T-Temperature ( °C)

vs. Temperature

80µs Pulsed Test

6

RDS(on) AT VGS =5V

Ip=200mA

80

8

Vosini AT Io=1mA

Vos=Vos

120

10



**BSS138** 

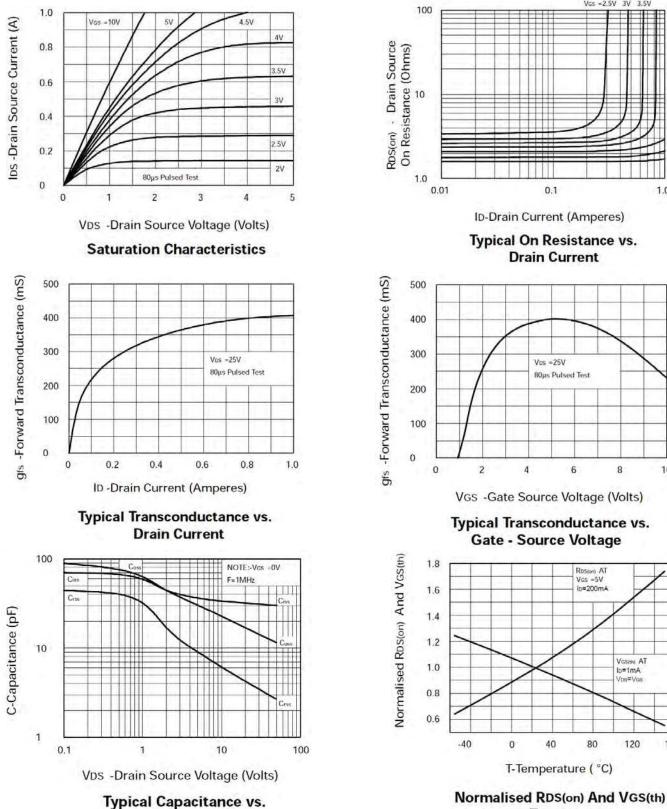
4V

71 10V

1.0

Vcs = 2.5V 3V 3.5V

## **Electrical Characteristics**



**Drain - Source Voltage** 

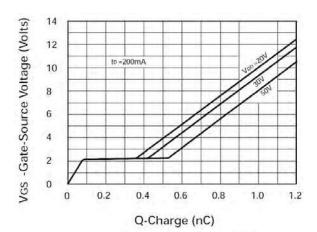
160

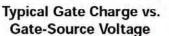


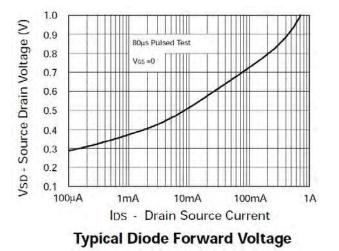


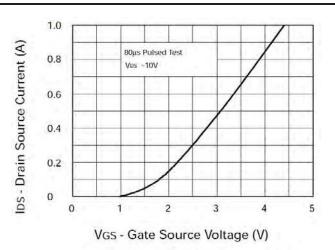


# **Electrical Characteristics – (Continuous)**









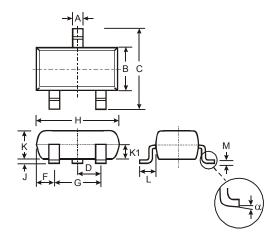
### **Typical Transfer Characteristics**





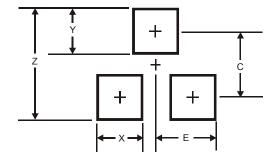


# Package Outline Dimensions



SOT23					
Dim	Min	Max	Тур		
Α	0.37	0.51	0.40		
В	1.20	1.40	1.30		
С	2.30	2.50	2.40		
D	0.89	1.03	0.915		
F	0.45	0.60	0.535		
G	1.78	2.05	1.83		
Н	2.80	3.00	2.90		
J	0.013	0.10	0.05		
К	0.903	1.10	1.00		
K1	-	-	0.400		
L	0.45	0.61	0.55		
М	0.085	0.18	0.11		
α	0°	8°	-		
All Dimensions in mm					

# Suggested Pad Layout



Dimensions	Value (in mm)		
Z	2.9		
Х	0.8		
Y	0.9		
С	2.0		
E	1.35		



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